

芯导科技 MOSFET 产品可靠性标准

Item	Test Name	Condition	Duration	Sample Size	Criteria (Acc/Rej)	Reference Standard	Remark
1	Precon	MSL soak + 3cycle reflow@ 260°C MSL1: 85°C/85% RH 168 (+5/-0)hrs MSL3: 30°C/60% RH 192 (+5/-0)hrs	-	Sum. of Item 2,3,4	0/1	JESD22-A113 J-STD-020	Applied to Surface Mount Devices
2	HAST	Ta=130°C, 85%RH, 2atmos, V=80%Vdsmax	96hrs	77*3	0/1	JESD22-A110	
2alt	THB	85°C/85% RH V=80%Vdsmax	168/ 500 / 1000 hours	77*3	0/1	JESD22-A101	
3	TC	-55°C~150°C	500/1000cyc	77*3	0/1	JESD22-A104	
4	PCT / PP / AC	121(±2)°C,RH=100% 29.7psia	96 hours	77*3	0/1	JESD22-A102	
4alt	UHASt	130(±2)°C,85(±5)%RH, 33.3psia	96 hours	77*3	0/1	JESD22-A118	
5	HTGB	T=Tj Vgs=100%Vgsmax	168 / 500 / 1000 hours	77*3	0/1	JESD22-A108	
6	HTRB	T=Tj, Vds=100%Vdsmax	168/ 500/ 1000 hours	77*3	0/1	JESD22-A108	
7	HTS	T=Tj	168/ 500 / 1000 hours	77*3	0/1	JESD22-A103	
8	Resistance to Solder Heat	270(+5/-0) °C	15(±1) seconds	30*3	0/1	JESD22-B106	Applied to Through-Hole Mounted Devices
		260(+5/-0) °C	10(±1) seconds	30*3	0/1	JESD22-A111	Applied to Surface Mount Devices
9	Solder ability	245±5 °C	5(±0.5) seconds	10*3	0/1	JESD22-B102	